



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IFX007T	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005709003		
<b>Package</b>	PG-TO263-7-1	<b>Weight*</b>	1535.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.963	0.13	0.13	1278	1278
chip_2	inorganic material	silicon	7440-21-3	4.129	0.27	0.27	2688	2688
chip_3	inorganic material	silicon	7440-21-3	1.222	0.08	0.08	795	795
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		527	
	non noble metal	copper	7440-50-8	808.613	52.65	52.72	526457	527142
wire	non noble metal	aluminium	7429-90-5	8.284	0.54	0.54	5393	5393
encapsulation	inorganic material	zinc oxide	1314-13-2	5.855	0.38		3812	
	miscellaneous	miscellaneous	-	23.422	1.52		15249	
	plastics	epoxy resin	-	87.832	5.72		57184	
	inorganic material	silicon dioxide	60676-86-0	468.438	30.50	38.12	304983	381228
lead finish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8488	8488
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	138	139
solder	non noble metal	tin	7440-31-5	0.107	0.01		70	
	noble metal	silver	7440-22-4	0.134	0.01		87	
	non noble metal	lead	7439-92-1	5.125	0.33	0.35	3336	3493
glue	plastics	Polyimide	26023-21-2	0.180	0.01	0.01	117	117
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.91	6.92	69149	69239
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com